

Power Inductor

Automotive Grade

AFDI Series



Overview

Power inductors are passive electronic components used in various circuits to store energy in a magnetic field when electrical current flows through them. They are critical in filtering, energy storage, and noise suppression in power electronic systems. They are designed to handle higher currents and are optimized for minimal power loss and thermal efficiency.

Benefits

1. Automotive grade available
2. Large size bottom termination
3. Low DCR
4. Large current

Applications

1. Automotive Systems
2. VRM/VRD
3. Industrial Control

Product Information

Series	L (mm)	W(mm)	T (mm)	Inductance (μH)
AFDI	12.0	12.0	9.0	0.47 ~ 120
	12.0	12.0	10.0	
	13.0	12.0	10.5	
	13.0	12.0	12.0	
	13.0	12.0	11.0	
	13.0	12.0	10.0	
	12.0	13.0	8.0	
	15.5	13.0	11.0	
	15.5	13.0	10.0	
	15.5	13.0	10.4	
	15.5	13.0	12.0	
	19.5	19.0	8.5	
	20.5	20.0	9.5	
	28.0	28.0	10.5	
	30.0	30.0	12.7	



Power Inductor

Automotive Grade

AFDI Series



Overview

Power inductors are passive electronic components used in various circuits to store energy in a magnetic field when electrical current flows through them. They are critical in filtering, energy storage, and noise suppression in power electronic systems. They are designed to handle higher currents and are optimized for minimal power loss and thermal efficiency.

Benefits

1. Automotive grade available
2. Large size bottom termination
3. Low DCR
4. Large current

Applications

1. Automotive Systems
2. VRM/VRD
3. Industrial Control

Product Information

Series	L (mm)	W(mm)	T (mm)	Inductance (μH)
AFDI	12.0	12.0	9.0	0.47 ~ 120
	12.0	12.0	10.0	
	13.0	12.0	10.5	
	13.0	12.0	12.0	
	13.0	12.0	11.0	
	13.0	12.0	10.0	
	12.0	13.0	8.0	
	15.5	13.0	11.0	
	15.5	13.0	10.0	
	15.5	13.0	10.4	
	15.5	13.0	12.0	
	19.5	19.0	8.5	
	20.5	20.0	9.5	
	28.0	28.0	10.5	
	30.0	30.0	12.7	

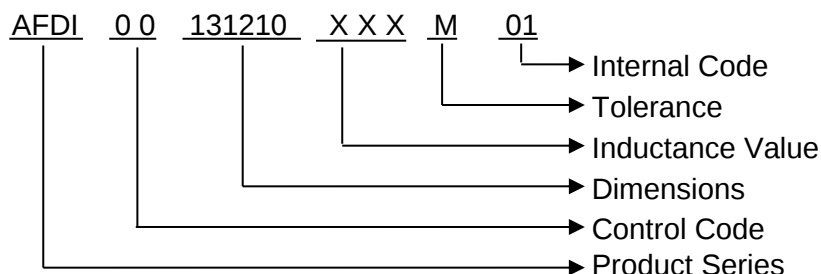


AFDI00131210XXXM01 Series Specification

AEC-Q200

1 Scope: This specification applies to large current and low RDC DIP power inductor.

2 Part Numbering:

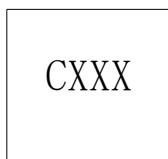


3 Rating:

Operating temperature range: $-50^{\circ}\text{C} \sim 150^{\circ}\text{C}$ (Including self - temperature rise)

Storage condition: $-20^{\circ}\text{C} \sim 40^{\circ}\text{C}$; 75%RH Max

4 Marking:



Marking color : White

Marking : **C** → Chilisin
XXX → Inductance

5 Material List:

NO	Part	Material
1	Copper Wire	EIAIW (200°C)
2	Core	Iron powder
3	coating	Paint Gray (127# matte)
4	Solder	Sn96.5-Ag3.0-Cu0.5
5	Ink	M23-092(PIC-1083B白)

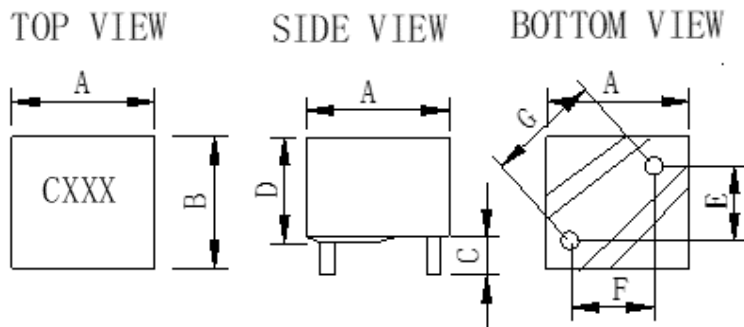
6 Standard Testing Condition

	Unless otherwise specified	In case of doubt
Temperature	Ordinary Temperature(15 to 35°C)	20 to 30°C
Humidity	Ordinary Humidity(25 to 85% RH)	50 to 80 %RH

AFDI00131210XXXM01 Series Specification

AEC-Q200

7 Configuration and Dimensions:



Product appearance



Part No.	A	B	C	D	E	F	G	H
AFDI00131210R60M01	13.0±0.5	12.0±0.5	3.4±0.5	10.0Max	6.6±0.5	7.6±0.5	10.0±0.5	Φ1.5±0.1
AFDI00131210R68M01	13.0±0.5	12.0±0.5	3.5±0.5	8.0Max	6.5±0.5	7.6±0.5	10.0±0.5	Φ1.5±0.1
AFDI001312101R0M01	13.0±0.5	12.0±0.5	3.4±0.5	10.0Max	6.6±0.5	7.6±0.5	10.0±0.5	Φ1.5±0.1
AFDI001312101R5M01	13.0±0.5	12.0±0.5	3.4±0.5	11.0Max	6.6±0.5	7.6±0.5	10.0±0.5	Φ1.2±0.1
AFDI01312102R2M01	13.0±0.5	12.0±0.5	3.4±0.5	10.5Max	6.6±0.5	7.6±0.5	10.0±0.5	Φ1.3±0.1
AFDI01312102R5M01	13.0±0.5	12.0±0.5	3.4±0.5	10.5Max	6.6±0.5	7.6±0.5	10.0±0.5	Φ1.3±0.1
AFDI001312103R3M01	13.0±0.5	12.0±0.5	3.4±0.5	12.0Max	6.6±0.5	7.6±0.5	10.0±0.5	Φ1.2±0.1
AFDI01312104R7M01	13.0±0.5	12.0±0.5	3.4±0.5	12.0Max	6.6±0.5	7.6±0.5	10.0±0.5	Φ1.3±0.1

8 Electrical Characteristics:

Part No.	Inductance (uH)	Test Freq.	Tolerance (±%)	I _{rms} (A)Typ.	I _{sat} (A)Typ.	RDC (mΩ)Max	Marking
AFDI00131210R60M01	0.60	100kHz,1.0V	20	35	45	1.0(0.88typ)	CR60
AFDI00131210R68M01	0.68	100kHz,1.0V	20	45	50	0.88(0.83typ)	CR68
AFDI001312101R0M01	1.0	100kHz,1.0V	20	30	40	1.32(1.12typ)	C1R0
AFDI001312101R5M01	1.5	100kHz,1.0V	20	26	40	2.0(1.81typ)	C1R5
AFDI001312102R2M01	2.2	100kHz,1.0V	20	20	20	2.0(1.85typ)	C2R2
AFDI001312102R5M01	2.5	100kHz,1.0V	20	28	34	2.8(2.44typ)	C2R5
AFDI001312103R3M01	3.3	100kHz,1.0V	20	19	23	4.0(2.55typ)	C3R3
AFDI001312104R7M01	4.7	100kHz,1.0V	20	20	20	6.0(4.28typ)	C4R7

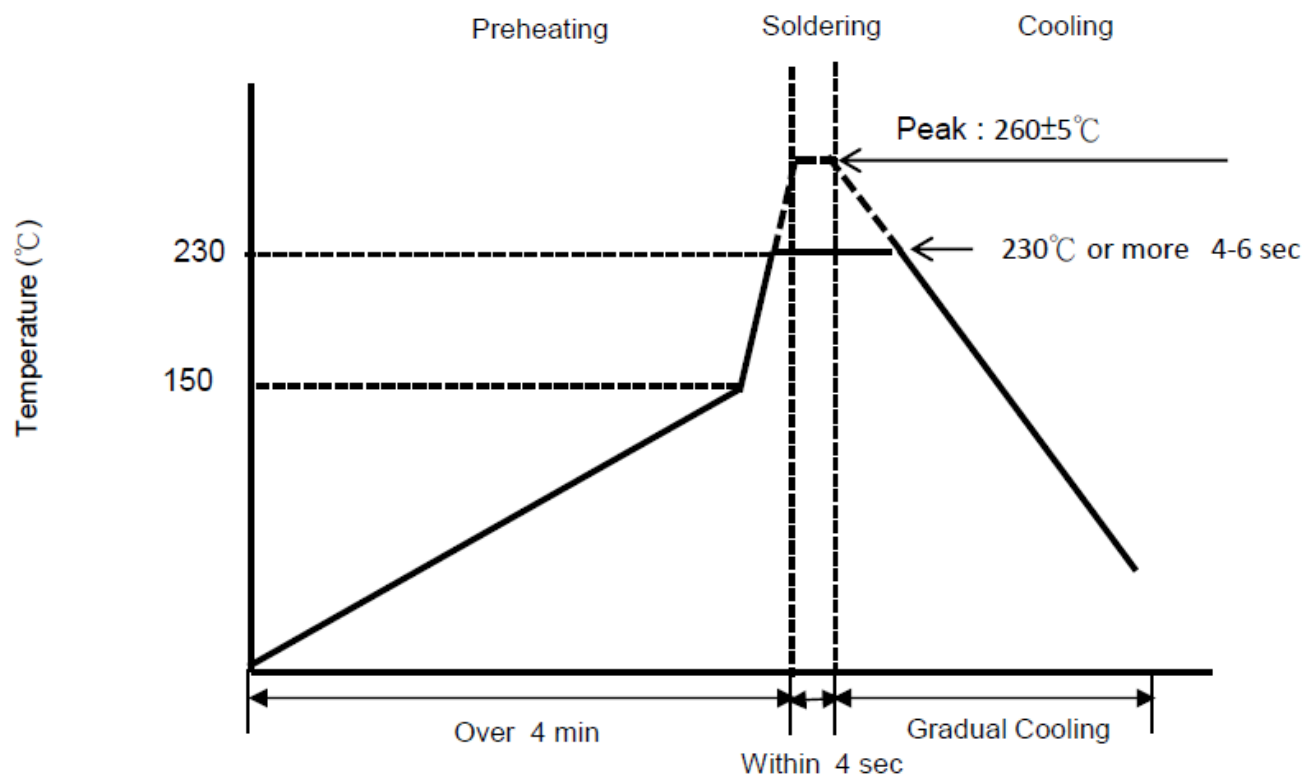
Note:

- 1.Ambient + temperature rise range — 50°C~150°C(Including self - temperature rise)
- 2.I_{sat} for Inductance drop 20% from its value without current.
- 3.I_{rms} for a 40°C temprature rise from 25°C ambient.
- 4.The part temperature (ambient + temp rise) should not exceed 150°C under worst case operating conditions.
Circuit design150°C under worst case operating conditions. Component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

9 Reliability verification conditions

No.	Stress	Reference	Test Conditions	Sample Size	Specification	Result
1	High Temperature Exposure (Storage)	MIL-STD-202 Method 108	1000 hrs. at rated operating temperature, part can be stored for 1000 hrs. @ 150°C. Unpowered. Measurement at 24±4 hours after test conclusion.	77	1. Electrical characterization-Inductance change range 2. Appearance-No damage	Pass
2	Temperature Cycling	JESD22 Method JA-104	1000 cycles (-50°C to +150°C). Measurement at 24±4 hours after test conclusion. 30 min maximum dwell time at each temperature extreme. 1 min.	77	1. Electrical characterization-Inductance change range 2. Appearance-No damage	Pass
3	Biased Humidity	MIL-STD-202 Method 103	1000 hours 85°C/85%RH. Unpowered. Measurement at 24±4 hours after test conclusion.	77	1. Electrical characterization-Inductance change range 2. Appearance-No damage	Pass
4	Operational Life	MIL-PRF-27	1000 hrs. @ 150 °C. Measurement 24±4 hours after test conclusion.	77	1. Electrical characterization-Inductance change range 2. Appearance-No damage	Pass
5	Physical Dimension	JESD22 Method JB-100	Verify physical dimensions to the applicable device detail specification.	15	Product spec	Pass
6	Resistance to Solvents	MIL-STD-202 Method 215	Immersion 3+0.5/-0 minutes in Terpene defluxer. Brush 10 strokes (wet bristle) 2 to 3 oz. Rinse in water. Air blow dry.	5	1. Marking resistance to solvent-No constitute failure (≤3X magnification) 2. Component protective coating, encapsulation material and sleeve material resistance- No damage or degradation that has occurred due to solvent (10X magnification)	Pass
7	Mechanical Shock	MIL-STD-202 Method 213	Units are non-operating. Pulse shape : Half-sine waveform Impact acceleration : 100 g's Pulse duration : 6 ms Number of shocks : 18 shocks (3 shocks 5 g's for 20 minutes, 12 cycles each of 3 orientations. Note: Use 8"X5" PCB, .031" thick, 7 secure points on the long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10-2000Hz.	30	1. Electrical characterization-Inductance change range 2. Appearance-No damage (OM)	Pass
8	Vibration	MIL-STD-202 Method 204	5 g's for 20 minutes, 12 cycles each of 3 orientations. Note: Use 8"X5" PCB, .031" thick, 7 secure points on the long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10-2000Hz.	30	1. Electrical characterization-Inductance change range 2. Appearance-No damage (OM)	Pass
9	Resistance to Soldering Heat	MIL-STD-202 Method 210	Test condition B: Solder dip-260±5°C (solder temp.), time 10±1 sec, immersion rate 25mm/s ±6 mm/s, 1 heat cycle.	30	1. Electrical characterization-Inductance change range 2. Appearance-No damage	Pass
10	Solderability	J-STD-002	Pre-condition: Steam 8hr±15min @93° C. For both Leaded & SMD. Electrical test not required. Magnification 50X. Test Method B @ 245±5°C, dwell for 5+0/-0.5 seconds	15	All terminations shall exhibit a continuous solder coating free from defects for a minimum of 95% of the critical area of any individual termination. (10X magnification)	Pass
11	Board Flex	AEC-Q200-005	Bend the board (D) X =2mm, 60sec minimum holding time.	30	No cracks	Pass
12	Terminal Strength	AEC-Q200-008	Apply a 1.8Kg force to the side of a device bending tested. The force shall be applied for 60+1 seconds.	30	No cracking or no part being sheared off from its pad	Pass

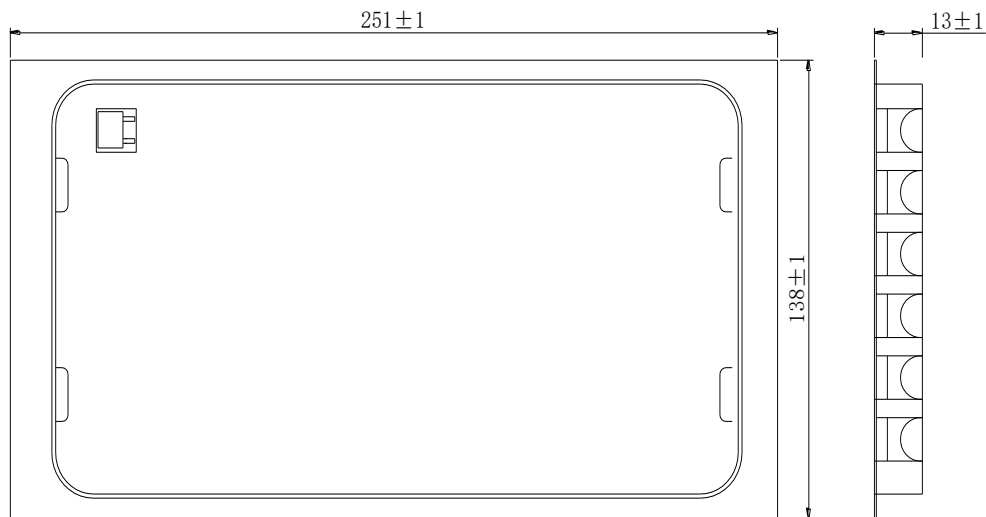
10 Wave Soldering:



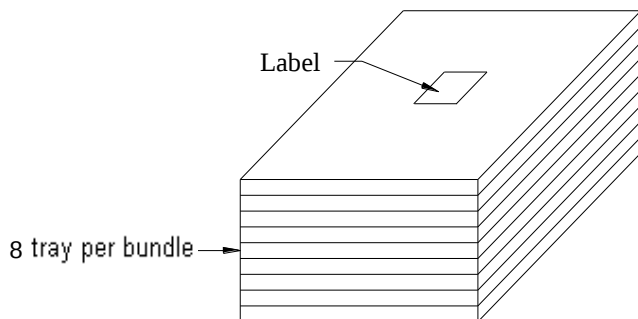
AFDI00131210XXM01 Series Specification

14 Packaging:

14.1 Small Pack: 50pcs per tray

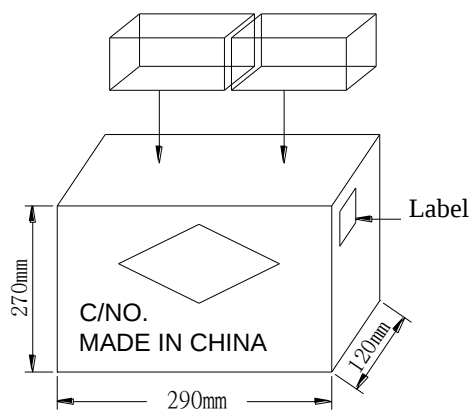


14.2 Medium pack: 8 tray per bundle (400pcs)



Inner carton number	
Partition	M08.015
Desiccant	M66.002
Plastic tray	M47.099
Label size	50*75mm
Label type	Self-adhesion
Label location	Top left corner

14.3 Large pack: 2 bundle per carton (800pcs)



Carton number	M08.032
Label location	Top left corner on side surface
Label size	75*100mm
Label type	Self-adhesion

13 Graph :

